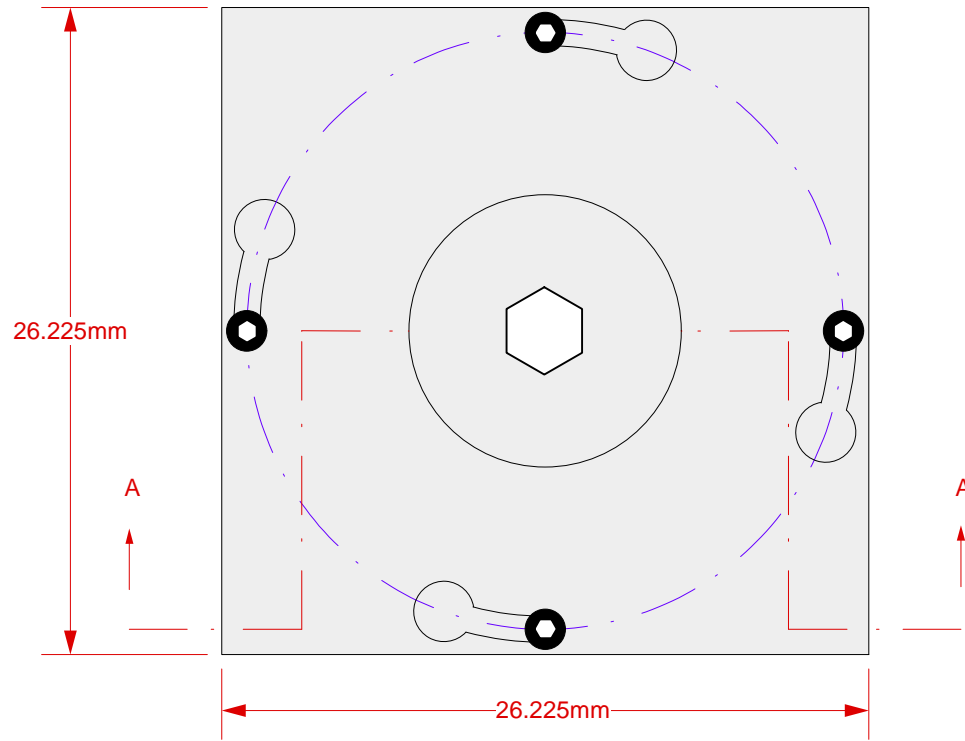


Top View

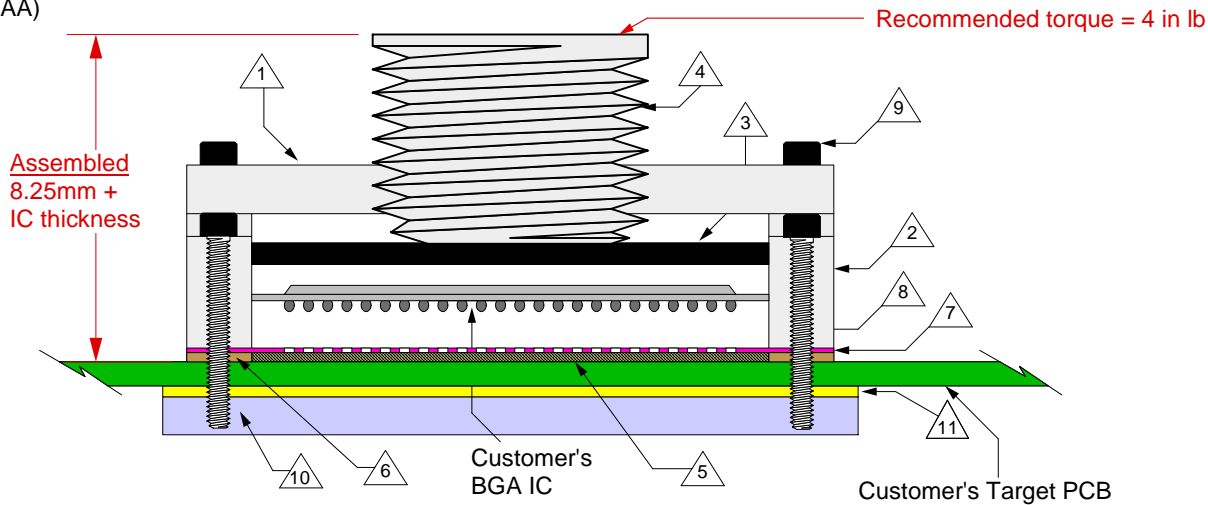


GHz BGA Socket - Direct mount, solderless


Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)

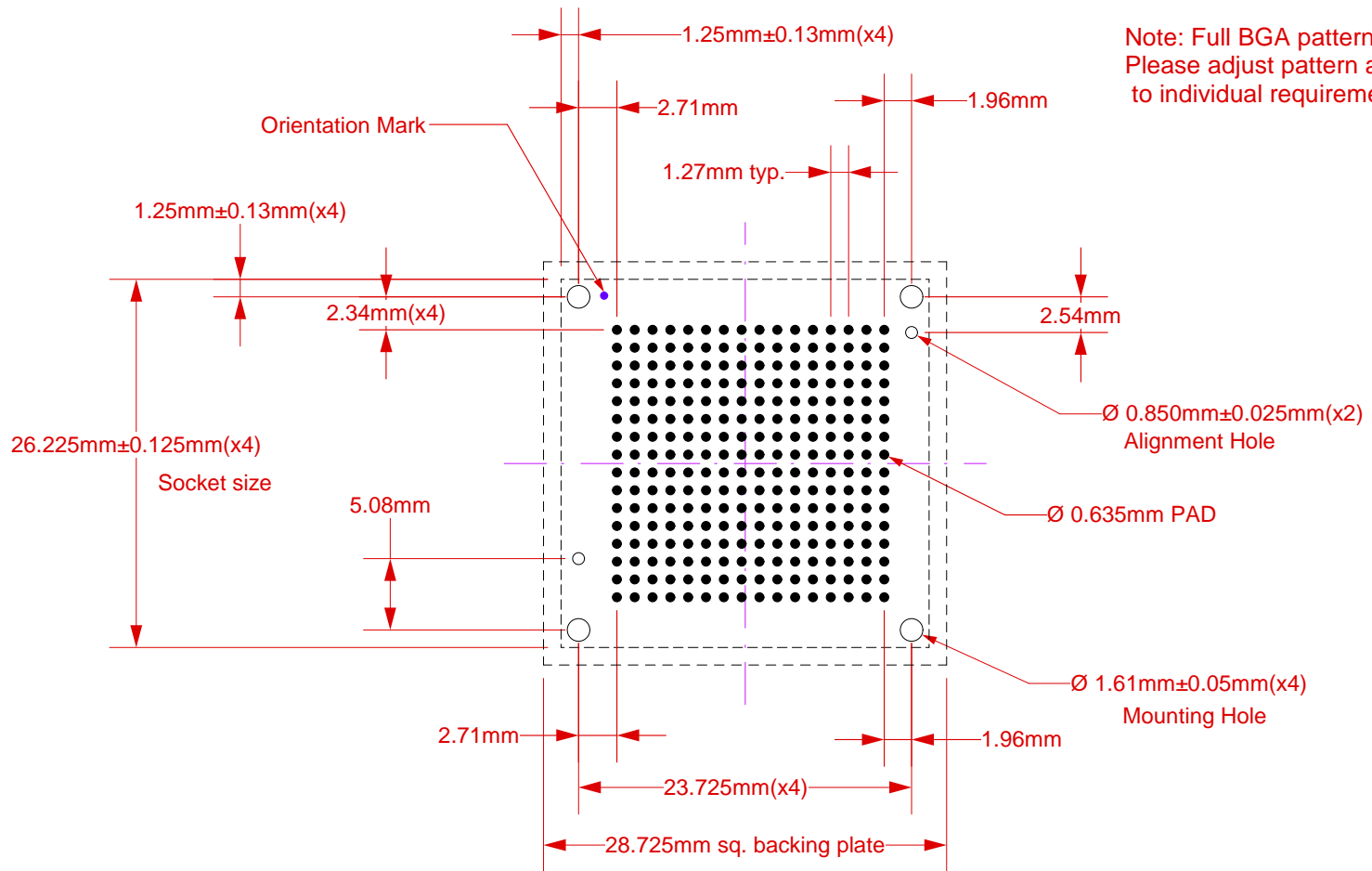


- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation Plate: FR4/G10, Thickness = 1.59mm. |
| 11 | Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm. |

	SG-BGA-6023 Drawing	Status: Released	Scale: NA	Rev: F
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 11/27/01
		File: SG-BGA-6023 Dwg.mcd	Modified: 7/16/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




Note: Full BGA pattern shown.
 Please adjust pattern according to individual requirements.

Target PCB Recommendations

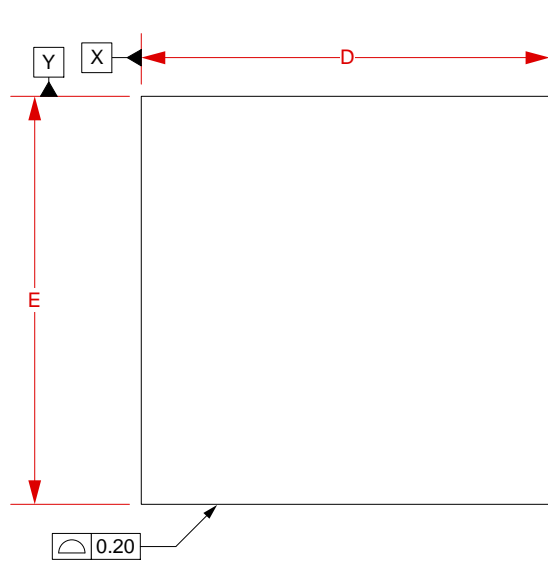
- Total thickness: 1.6mm min.
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

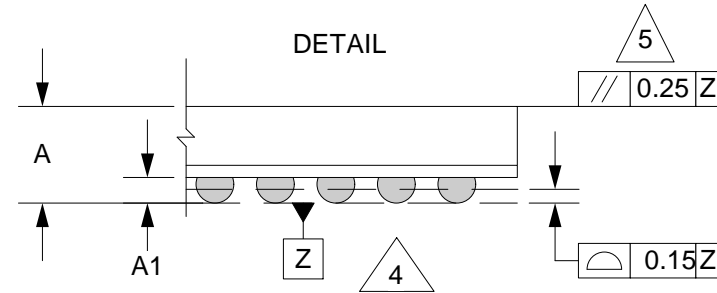
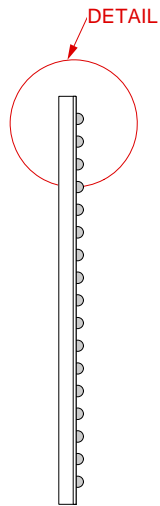
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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	Drawing: H. Hansen		Date: 11/27/01		
	File: SG-BGA-6023 Dwg.mcd		Modified: 7/16/09, AE		

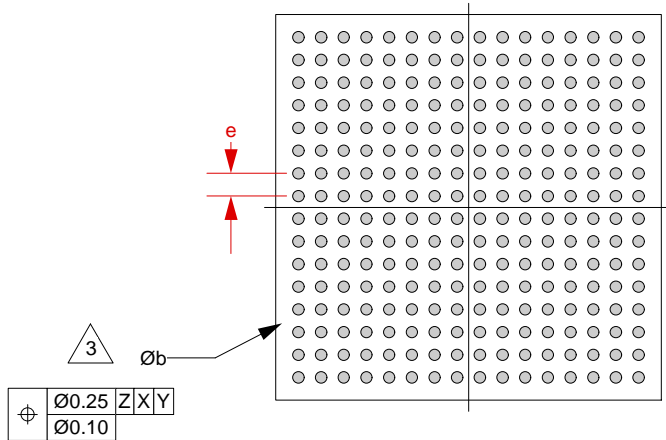
TOP VIEW
(Reference Only)



SIDE VIEW
(Reference Only)



BOTTOM VIEW
(Reference Only)




1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

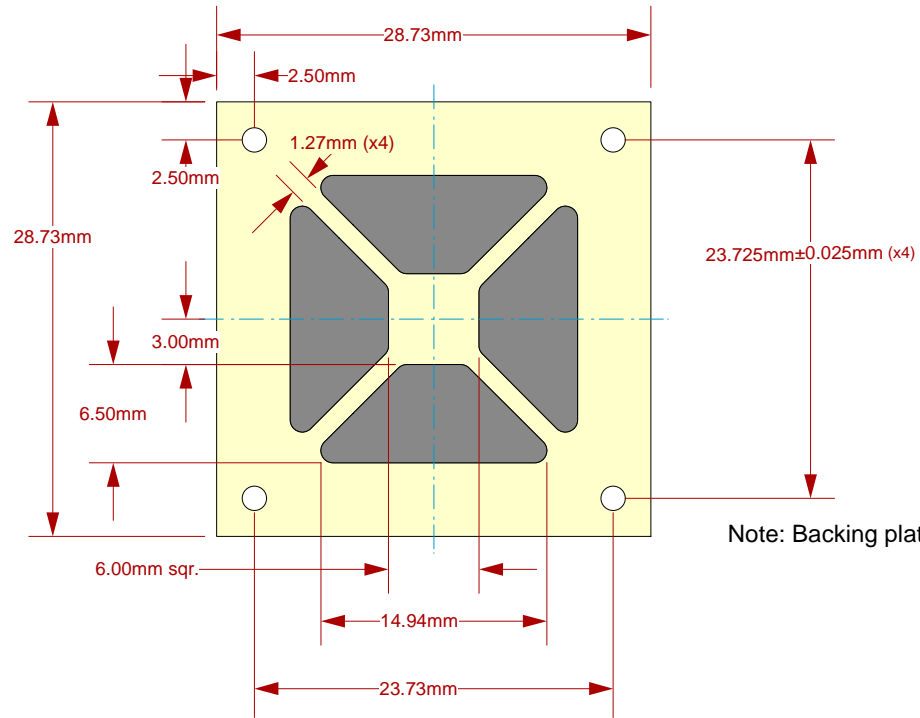
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		4.01
A1	0.74	0.94
b		1.0
D	21.00 BSC	
E	21.00 BSC	
e	1.27 BSC	

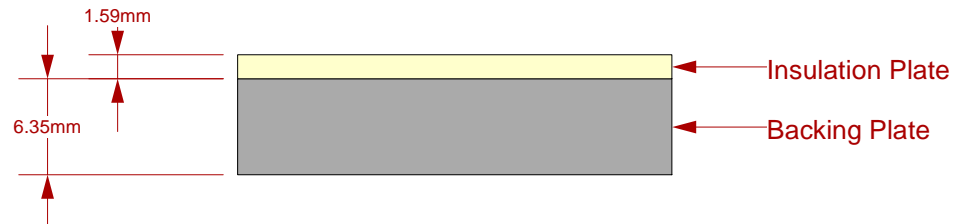
Array 16x16

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Top View



Side View



Description: Backing Plate with Insulation Plate

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	<p>Drawing: H. Hansen</p>	<p>Date: 11/27/01</p>		
	<p>File: SG-BGA-6023 Dwg.mcd</p>	<p>Modified: 7/16/09, AE</p>		